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31/12/2014

სსიპ-საგანმანათლებლო და სამეცნიერო ინფრასტრუქტურის განვითარების სააგენტოს
დირექტორის მაოდგილეს
ბატონ გიორგი შალუტაშვილს

ბ-ნ გიორგი,

გაცნობებთ, რომ მიმდინარე წლის 30 დეკემბერს ხელშეკრულება N32050102-32050101/01/266 ით
გათვალისწინებული ტექნიკური პარამეტრების ფაქტობრივთან შესაბამისობის დადგენის მიზნით
მოხდა აღნიშნული ტექნიკის შემოწმება სსიპ განათლების მართვის საინფორმაციოს სისტემის
სისტემური ადმინისტრატორის - ნიკა ბრეგვაძის და მონიტორინგის ჯგუფის მენეჯერის - ლევან
ბიძინაშვილის მიერ, რის შედეგადაც დადგინდა შემდეგი:

ფაქტობრივად წარმოდგენილი კომპიუტერული ტექნიკა (მაგიდის კომპიუტერები - დესკტოპები)
ნაწილობრივ შესაბამისობაშია ხელშეკრულებაში გათვალისწინებულთან, კერძოდ სხვაობაა ერთ
პარამეტრში:

ცენტრალური პროცესორის მოდელი ხელშეკრულებაში მითითებულია intel i3 4130, ხოლო
ფაქტიურად მოცემულია intel i3 4150. აღსანიშნავია ის გარემოება, რომ წარმოდგენილი პროცესორი
არის პარამეტრებით უფრო უკეთესი მოდელი ვიდრე ხელშეკრულებით გათვალისწინებული
(უკეთესობა გამოხატულია პროცესორის ტაქტურ სიხშირეში i3-4130 = 3.4Ghz, i3-4150 = 3.5 Ghz).
წარმოდგენილი კომპიუტერის პროცესორს 0,1Mhz ით უფროს მეტი ტაქტური სიხშირე აქვს, ხოლო
დანარჩენი ყველა პარამეტრი იდენტურია. **(დეატლური ინფორმაციისთვის იხილეთ დართული
ოფიციალური მწარმოებლის დოკუმენტები).**

წარმოდგენილი ტექნიკის ყველა დანარჩენი ტექნიკური პარამეტრი სრულ თანხვედრაშია ხელშეკრულებაში მოცემულთან.


პატივიცემით,



Intel® Core™ i3-4130 Processor (3M Cache, 3.40 GHz)

Specifications

- Essentials

Status	Launched
Launch Date	Q3'13
Processor Number	i3-4130
Intel® Smart Cache	3 MB
DMI2	5 GT/s
# of QPI Links	0
Instruction Set	64-bit
Instruction Set Extensions	SSE4.1/4.2 AVX2.0
Embedded Options Available	 No
Lithography	22 nm
Scalability	1S Only
Thermal Solution Specification	PCG 2013C
Recommended Customer Price	BOX : \$117.00 TRAY : \$117.00
Conflict Free	Yes
Datasheet	Link

- Performance











# of Cores	2
# of Threads	4
Processor Base Frequency	3.4 GHz
TDP	54 W

- Memory Specifications

Max Memory Size (dependent on memory type)	32 GB
Memory Types	DDR3-1333/1600
# of Memory Channels	2
Max Memory Bandwidth	25.6 GB/s
ECC Memory Supported †	 Yes

- Graphics Specifications

Processor Graphics †	Intel® HD graphics 4400
Graphics Base Frequency	350 MHz

Graphics Max Dynamic Frequency		1.15 GHz
Graphics Video Max Memory		1.7 GB
Intel® Quick Sync Video		Yes
Intel® InTru™ 3D Technology		Yes
Intel® Wireless Display		Yes
Intel® Clear Video HD Technology		Yes
# of Displays Supported †		3
- Expansion Options		
PCI Express Revision		3.0
PCI Express Configurations †		Up to 1x16, 2x8, 1x8/2x4
Max # of PCI Express Lanes		16
- Package Specifications		
Max CPU Configuration		1
T _{CASE}		72°C
Package Size		37.5mm x 37.5mm
Graphics and IMC Lithography		22nm
Sockets Supported		FCLGA1150
Low Halogen Options Available		See MDDS
- Advanced Technologies		
Intel® Turbo Boost Technology †		No
Intel® vPro Technology †		No
Intel® Hyper-Threading Technology †		Yes
Intel® Virtualization Technology (VT-x) †		Yes
Intel® Virtualization Technology for Directed I/O (VT-d) †		No
Intel® VT-x with Extended Page Tables (EPT) †		Yes
Intel® TSX-NI		No
Intel® 64 †		Yes
Idle States		Yes
Enhanced Intel SpeedStep® Technology		Yes
Thermal Monitoring Technologies		Yes
Intel® Stable Image Platform Program (SIPP)		No
- Intel® Data Protection Technology		
AES New Instructions		Yes
- Intel® Platform Protection Technology		
Trusted Execution Technology †		No

Execute Disable Bit †

Yes

Compatible Products

[Find Compatible Desktop Boards >](#)

- Chipsets

Compare	Product Name	Status	Embedded Options Available	TDP	Recommended Customer Price
Compare All +					
	Intel® Z97 Chipset (Intel® DH82Z97 PCH)	Launched	No	4.1 W	N/A
	Intel® H97 Chipset (Intel® DH82H97 PCH)	Launched	No	4.1 W	N/A
	Intel® Z87 Chipset (Intel® DH82Z87 PCH)	Launched	No	4.1 W	N/A
	Intel® Q87 Chipset (Intel® DH82Q87 PCH)	Launched	Yes	4.1 W	T&R: \$47.00
	Intel® H87 Chipset (Intel® DH82H87 PCH)	Launched	No	4.1 W	T&R: \$32.00
	Intel® B85 Chipset (Intel® DH82B85 PCH)	Launched	No	4.1 W	T&R: \$28.00
	Intel® Q85 Chipset (Intel® DH82Q85 PCH)	Launched	No	4.1 W	N/A
	Intel® H81 Chipset (Intel® DH82H81 PCH)	Launched	Yes	4.1 W	T&R: \$26.00

- System

Compare	Product Name	Status	Chassis Form Factor	Board Form Factor	Socket
Compare All +					
	Intel® Server System R1208RPMSHOR	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1208RPOSHOR	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1304RPMSHOR	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1304RPOSHBN	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1304RPSSFBN	Launched	Rack	Custom 16.7" x 17"	Socket R3
	Intel® Server System P4308RPLSHDR	Launched	4U Pedestal	uATX	LGA1150

- Server/Workstation Board

Compare	Product Name	Status	Board Form Factor	Chassis Form Factor	Socket	Embedded Options Available	TDP
Compare All +							
	Intel® Server Board S1200V3RPL	Launched	uATX	4U Rack or Pedestal	LGA1150	Yes	95 W
	Intel® Server Board S1200V3RPM	Launched	uATX	1U Rack	LGA1150	Yes	95 W
	Intel® Server Board S1200V3RPO	Launched	uATX	1U Rack	LGA1150	No	95 W

	Intel® Server Board S1200V3RPS	Launched	uATX	Rack or Pedestal	LGA1150	No	95 W
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Ordering and Spec Information

Trade Compliance Information

ECCN	CCATS	US HTS
5A992C	G077159	8542310000-HYBRD

Ordering and Spec Information

Spec Code	Ordering Code	Step	RCP	VT-x
Boxed Intel® Core™ i3-4130 Processor (3M Cache, 3.40 GHz) FC-LGA12C				
SR1NP	BX80646I34130	C0	\$117.00	
Boxed Intel® Core™ i3-4130 Processor (3M Cache, 3.40 GHz) FC-LGA12C, for China				
SR1NP	BXC80646I34130	C0	N/A	
Intel® Core™ i3-4130 Processor (3M Cache, 3.40 GHz) FC-LGA12C, Tray				
SR1NP	CM8064601483615	C0	\$117.00	Yes

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading> for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see <http://www.intel.com/performance>.



Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.











Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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Intel® Core™ i3-4150 Processor (3M Cache, 3.50 GHz)

Specifications	
- Essentials	
Status	Launched
Launch Date	Q2'14
Processor Number	i3-4150
Intel® Smart Cache	3 MB
DMI2	5 GT/s
# of QPI Links	0
Instruction Set	64-bit
Instruction Set Extensions	SSE4.1/4.2 AVX2.0
Embedded Options Available	 No
Lithography	22 nm
Scalability	1S Only
Thermal Solution Specification	PCG 2013C
Recommended Customer Price	BOX : \$117.00 TRAY : \$117.00
Conflict Free	Yes
Datasheet	Link
- Performance	
# of Cores	2
# of Threads	4
Processor Base Frequency	3.5 GHz
TDP	54 W
- Memory Specifications	
Max Memory Size (dependent on memory type)	32 GB
Memory Types	DDR3-1333/1600
# of Memory Channels	2
Max Memory Bandwidth	25.6 GB/s
ECC Memory Supported †	 Yes
- Graphics Specifications	
Processor Graphics †	Intel® HD Graphics 4400
Graphics Base Frequency	350 MHz

Graphics Max Dynamic Frequency		1.15 GHz
Graphics Video Max Memory		1.7 GB
Intel® Quick Sync Video		Yes
Intel® InTru™ 3D Technology		Yes
Intel® Wireless Display		Yes
Intel® Clear Video HD Technology		Yes
# of Displays Supported †		3
- Expansion Options		
PCI Express Revision		3.0
PCI Express Configurations †		Up to 1x16, 2x8, 1x8/2x4
Max # of PCI Express Lanes		16
- Package Specifications		
Max CPU Configuration		1
T _{CASE}		72°C
Package Size		37.5mm x 37.5mm
Graphics and IMC Lithography		22nm
Sockets Supported		FCLGA1150
Low Halogen Options Available		See MDDS
- Advanced Technologies		
Intel® Turbo Boost Technology †		No
Intel® vPro Technology †		No
Intel® Hyper-Threading Technology †		Yes
Intel® Virtualization Technology (VT-x) †		Yes
Intel® Virtualization Technology for Directed I/O (VT-d) †		No
Intel® VT-x with Extended Page Tables (EPT) †		Yes
Intel® TSX-NI		No
Intel® 64 †		Yes
Idle States		Yes
Enhanced Intel SpeedStep® Technology		Yes
Thermal Monitoring Technologies		Yes
Intel® Stable Image Platform Program (SIPP)		No
- Intel® Data Protection Technology		
AES New Instructions		Yes
- Intel® Platform Protection Technology		
Trusted Execution Technology †		No

Execute Disable Bit †

Yes

Compatible Products

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- Chipsets

Compare	Product Name	Status	Embedded Options Available	TDP	Recommended Customer Price
Compare All +					
	Intel® Z97 Chipset (Intel® DH82Z97 PCH)	Launched	No	4.1 W	N/A
	Intel® H97 Chipset (Intel® DH82H97 PCH)	Launched	No	4.1 W	N/A
	Intel® Z87 Chipset (Intel® DH82Z87 PCH)	Launched	No	4.1 W	N/A
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	Intel® H87 Chipset (Intel® DH82H87 PCH)	Launched	No	4.1 W	T&R: \$32.00
	Intel® B85 Chipset (Intel® DH82B85 PCH)	Launched	No	4.1 W	T&R: \$28.00
	Intel® Q85 Chipset (Intel® DH82Q85 PCH)	Launched	No	4.1 W	N/A
	Intel® H81 Chipset (Intel® DH82H81 PCH)	Launched	Yes	4.1 W	T&R: \$26.00

- System

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Compare All +					
	Intel® Server System R1208RPMSHOR	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1208RPOSHOR	Launched	1U Rack	uATX	LGA1150
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	Intel® Server System R1304RPOSHBN	Launched	1U Rack	uATX	LGA1150
	Intel® Server System R1304RPSSFBN	Launched	Rack	Custom 16.7" x 17"	Socket R3
	Intel® Server System P4308RPLSHDR	Launched	4U Pedestal	uATX	LGA1150

- Server/Workstation Board

Compare	Product Name	Status	Board Form Factor	Chassis Form Factor	Socket	Embedded Options Available	TDP
Compare All +							
	Intel® Server Board S1200V3RPL	Launched	uATX	4U Rack or Pedestal	LGA1150	Yes	95 W
	Intel® Server Board S1200V3RPM	Launched	uATX	1U Rack	LGA1150	Yes	95 W
	Intel® Server Board S1200V3RPO	Launched	uATX	1U Rack	LGA1150	No	95 W

	Intel® Server Board S1200V3RPS	Launched	uATX	Rack or Pedestal	LGA1150	No	95 W
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Ordering and Spec Information

Trade Compliance Information

ECCN	CCATS	US HTS
5A992C	G077159	8542310000-HYBRD

Ordering and Spec Information

Spec Code	Ordering Code	Step	RCP
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SR1PJ	BX80646I34150	CO	\$117.00
Boxed Intel® Core™ i3-4150 Processor (3M Cache, 3.50 GHz) FC-LGA12C, for China			
SR1PJ	BXC80646I34150	CO	N/A
Intel® Core™ i3-4150 Processor (3M Cache, 3.50 GHz) FC-LGA12C, Tray			
SR1PJ	CM8064601483643	CO	\$117.00

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